

ChipFET™

DATE 19 MAY 2009

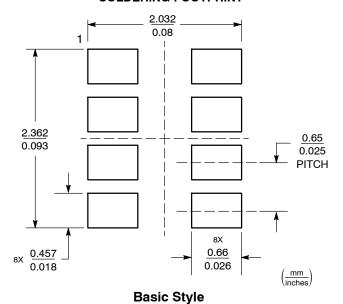
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- MOLD GATE BURRS SHALL NOT EXCEED 0.13 MM PER SIDE. LEADFRAME TO MOLDED BODY OFFSET IN HORIZONTAL
- AND VERTICAL SHALL NOT EXCEED 0.08 MM.
 DIMENSIONS A AND B EXCLUSIVE OF MOLD GATE BURRS.
- NO MOLD FLASH ALLOWED ON THE TOP AND BOTTOM LEAD SURFACE.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.00	1.05	1.10	0.039	0.041	0.043
b	0.25	0.30	0.35	0.010	0.012	0.014
С	0.10	0.15	0.20	0.004	0.006	0.008
D	2.95	3.05	3.10	0.116	0.120	0.122
E	1.55	1.65	1.70	0.061	0.065	0.067
е	0.65 BSC			0.025 BSC		
e1	0.55 BSC			0.022 BSC		
L	0.28	0.35	0.42	0.011	0.014	0.017
HE	1.80	1.90	2.00	0.071	0.075	0.079
θ	5° NOM			5° NOM		

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:	STYLE 5:	STYLE 6:
PIN 1. DRAIN	PIN 1. SOURCE 1	PIN 1. ANODE	PIN 1. COLLECTOR	PIN 1. ANODE	PIN 1. ANODE
DRAIN	2. GATE 1	2. ANODE	2. COLLECTOR	ANODE	2. DRAIN
DRAIN	SOURCE 2	SOURCE	COLLECTOR	DRAIN	3. DRAIN
GATE	4. GATE 2	4. GATE	4. BASE	DRAIN	4. GATE
SOURCE	5. DRAIN 2	5. DRAIN	EMITTER	SOURCE	5. SOURCE
DRAIN	6. DRAIN 2	6. DRAIN	COLLECTOR	GATE	6. DRAIN
DRAIN	7. DRAIN 1	CATHODE	COLLECTOR	CATHODE	7. DRAIN
8. DRAIN	8. DRAIN 1	CATHODE	COLLECTOR	CATHODE	8. CATHODE / DRAIN

SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

М = Month Code = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

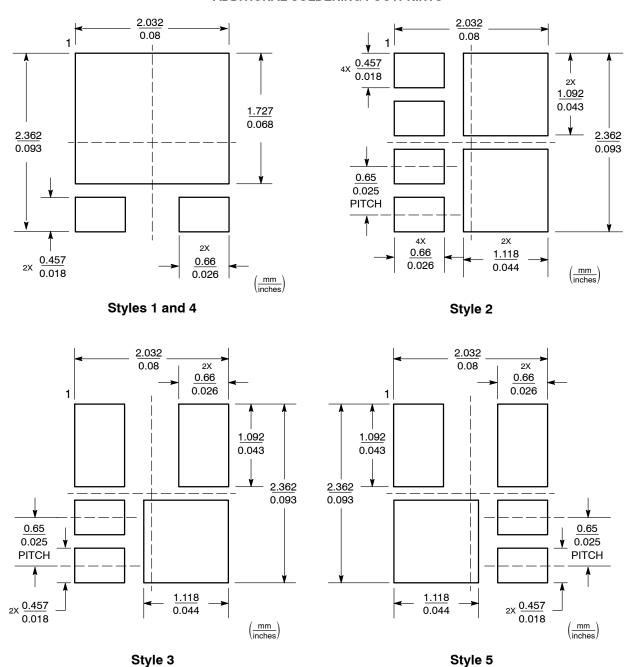
OPTIONAL SOLDERING FOOTPRINTS ON PAGE 2

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ADDITIONAL SOLDERING FOOTPRINTS*



*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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